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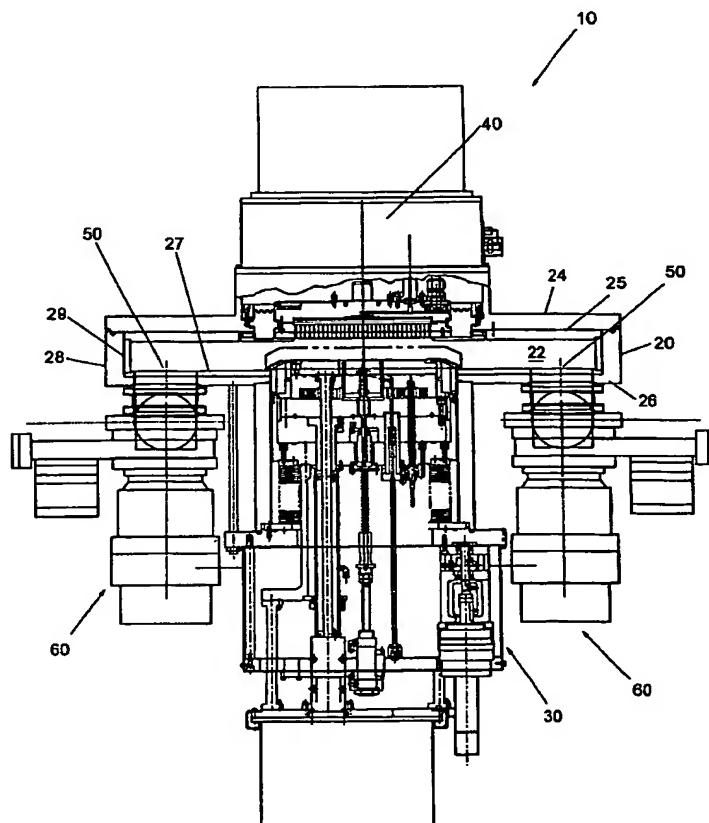
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(54) Title: REDUCED VOLUME, HIGH CONDUCTANCE PROCESS CHAMBER



(57) Abstract: A vacuum processing apparatus including a process chamber having a plurality of pumping ports, and a plurality of pumping cells each connected to a respective pumping port of the plurality of pumping ports. The plurality of pumping ports is preferably located on a lower wall of the process chamber adjacent to a process chamber volume. A process chamber is also provided that includes a lower wall and a side wall, where the side wall has a height of about four inches. The vacuum processing apparatus further includes a chamber liner configured to displace open volume within the process chamber.